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May 2014

FQA8N90C_F109

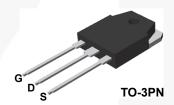
N-Channel QFET $^{\circledR}$ MOSFET 900 V, 8 A, 1.9 Ω

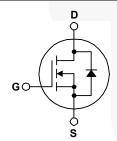
Features

- 8 A, 900 V, $R_{DS(on)} = 1.9 \Omega$ (Max.) @ $V_{GS} = 10 \text{ V}$, $I_D = 4 \text{ V}$
- Low Gate Charge (Typ. 35 nC)
- Low Crss (Typ. 12 pF)
- 100% Avalanche Tested
- · RoHS Compliant

Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQA8N90C_F109	Unit
V _{DSS}	Drain-Source Voltage		900	V
I _D	Drain Current - Continuous (T _C = 25°C)		8.0	Α
	- Continuous (T _C = 100°C)		5.1	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	32	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	850	mJ
I _{AR}	Avalanche Current	(Note 1)	8.0	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	24	mJ
dv/dt	Peak Diode Recovery dv/dt		4.0	V/ns
P _D	Power Dissipation (T _C = 25°C)		240	W
	- Derate above 25°C	1.92	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C	

Thermal Characteristics

Symbol	Parameter	FQA8N90C_F109	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.52	°C/W	
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.24	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	°C/W	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA8N90C_F109	FQA8N90C	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_{D} = 250 μ A	900			V
$\Delta BV_{DSS}/$ ΔT_{J}	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C		0.95		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 900 V, V _{GS} = 0 V		-	10	μА
		V _{DS} = 720 V, T _C = 125°C		-	100	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	-	1	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$		-	-100	nA
On Charact	teristics					•
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 4.0 \text{ A}$		1.6	1.9	Ω
g _{FS}	Forward Transconductance	$V_{DS} = 50 \text{ V}, I_{D} = 4.0 \text{ A}$	-	5.5		S
Dynamic Ch	haracteristics					
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,	\	1600	2080	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		130	170	pF
C _{rss}	Reverse Transfer Capacitance			12	15	pF
Switching C	Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 450 V, I _D = 11.0A,		40	90	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		110	230	ns
t _{d(off)}	Turn-Off Delay Time			70	150	ns
t _f	Turn-Off Fall Time	- (Note 4)		70	150	ns
Qg	Total Gate Charge	V _{DS} = 720 V, I _D = 11.0A,	/	35	45	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V	-/	10		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	<i>y</i> -	14		nC
Drain-Source	ce Diode Characteristics and Maximum Ratings					
I _S Maximum Continuous Drain-Source Diode Forward Current					8.0	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current			-	32.0	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 8.0 A			1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 8.0 \text{ A},$		530	-	ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs		5.8		μС

Notes

^{1.} Repetitive rating: pulse-width limited by maximum junction temperature.

^{2.} L = 25 mH, I_{AS} = 8 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C.

 $^{3.}I_{SD} \leq 8$ A, di/dt ≤ 200 A/µs, $V_{DD} \leq BV_{DSS},$ starting T_J = 25°C.

Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

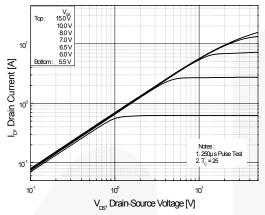


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

Figure 2. Transfer Characteristics

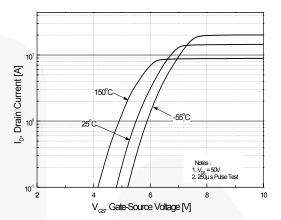


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

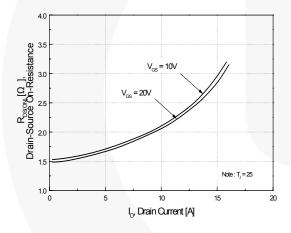


Figure 5. Capacitance Characteristics

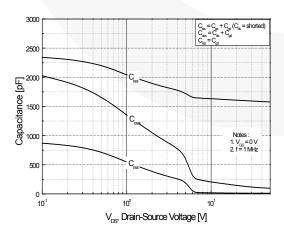
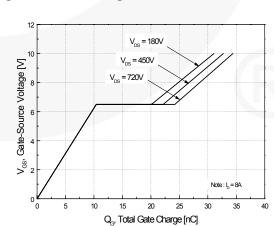
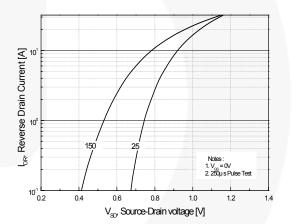


Figure 6. Gate Charge Characteristics





Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

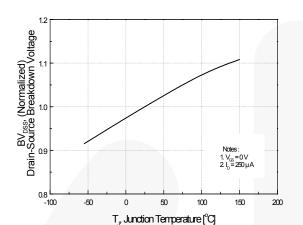


Figure 8. On-Resistance Variation vs. Temperature

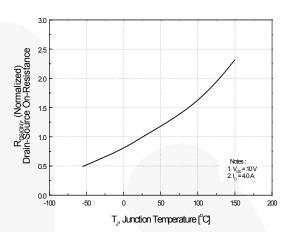
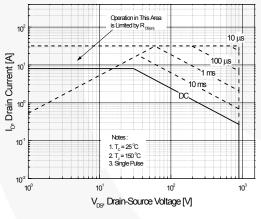


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature



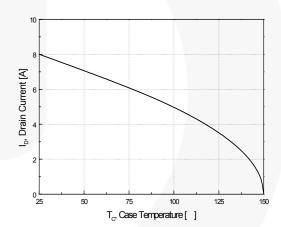
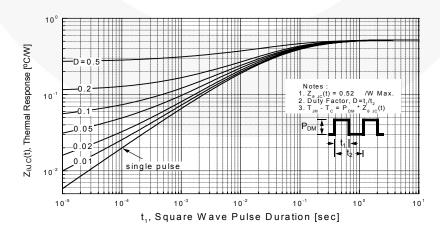


Figure 11. Transient Thermal Response Curve



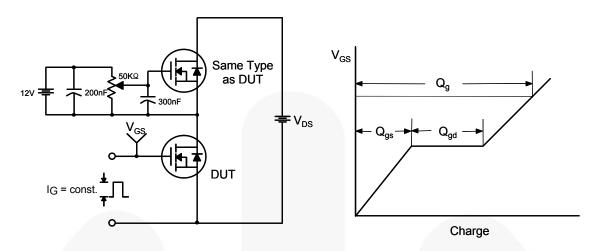


Figure 12. Gate Charge Test Circuit & Waveform

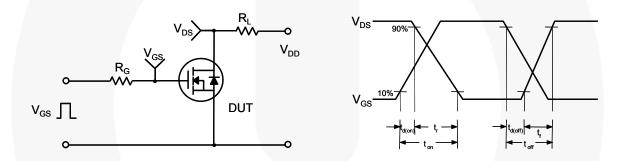


Figure 13. Resistive Switching Test Circuit & Waveforms

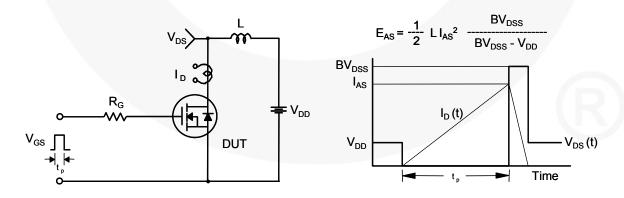


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

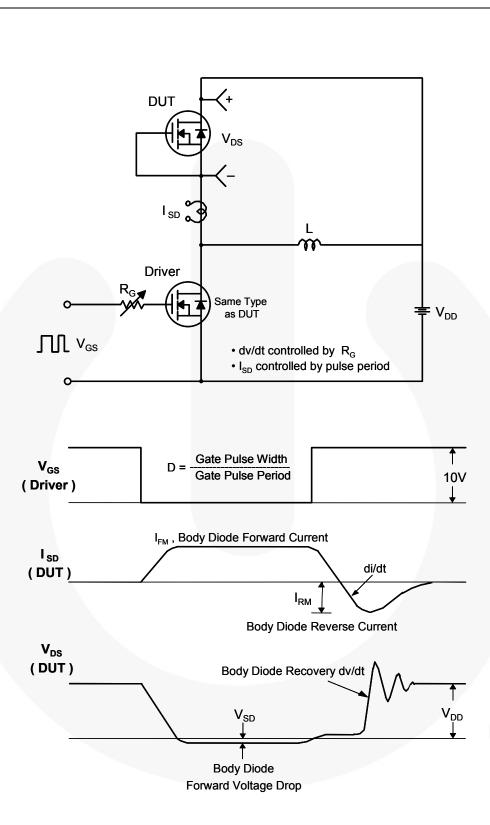
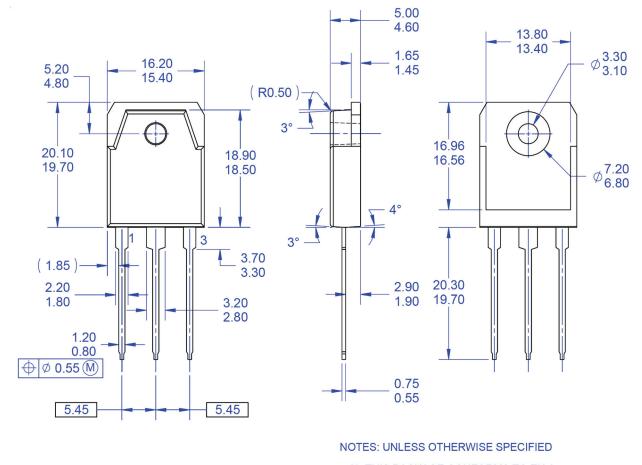
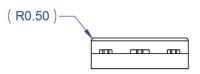


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions





- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
 B) ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
 E) DRAWING FILE NAME: TO3PN03AREV1.
- FAIRCHILD SEMICONDUCTOR.

Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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